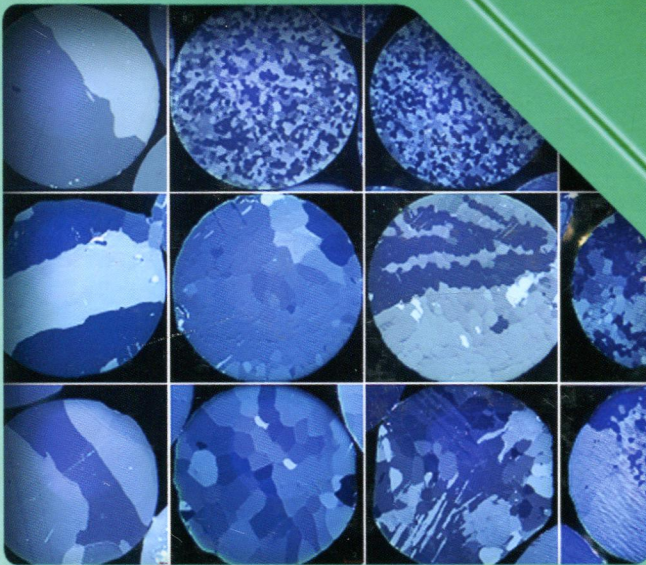


Edited by
K. N. Subramanian

Lead-free Solders

Materials Reliability
for Electronics



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Lead-free Solders: Materials Reliability for Electronics

Edited by

K. N. SUBRAMANIAN

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Contents

<i>Series Preface</i>	xv
<i>Preface</i>	xvii
<i>List of Contributors</i>	xix
Thematic Area I: Introduction	1
1 Reliability of Lead-Free Electronic Solder Interconnects: Roles of Material and Service Parameters	3
<i>K. N. Subramanian</i>	
1.1 Material Design for Reliable Lead-Free Electronic Solders Joints	3
1.2 Imposed Fields and the Solder Joint Responses that Affect Their Reliability	5
1.3 Mechanical Integrity	5
1.4 Thermomechanical Fatigue (TMF)	6
1.5 Whisker Growth	7
1.6 Electromigration (EM)	7
1.7 Thermomigration (TM)	8
1.8 Other Potential Issues	8
Thematic Area II: Phase Diagrams and Alloying Concepts	11
2 Phase Diagrams and Their Applications in Pb-Free Soldering	13
<i>Sinn-wen Chen, Wojciech Gierlotka, Hsin-jay Wu, and Shih-kang Lin</i>	
2.1 Introduction	14
2.2 Phase Diagrams of Pb-Free Solder Systems	14
2.3 Example of Applications	23
2.3.1 General Applications (Melting, Solidification, Interfacial Reactions)	23
2.3.2 Effective Undercooling Reduction (Co Addition)	28
2.3.3 Unexpected Compound Formation (Sn-Ag/Cu Interfacial Reactions)	32
2.3.4 Unexpected Growth Rates (Sn-Bi/Fe and Sn-Pb/Fe)	32
2.3.5 Unexpected Melting of Solder (Sn-Sb/Ag)	34
2.3.6 Up-Hill Diffusion (Sn-Cu/Ni)	36
2.3.7 Limited Sn Supply (Au/Sn/Cu)	39

2.4	Conclusions	39
	Acknowledgments	40
	References	41
3	Phase Diagrams and Alloy Development	45
	<i>Alan Dinsdale, Andy Watson, Ales Kroupa, Jan Vrestal, Adela Zemanova, and Pavel Broz</i>	
3.1	Introduction	45
3.2	Computational Thermodynamics as a Research Tool	48
3.2.1	Concept of the Calculation of Phase Diagrams for Multicomponent Systems	48
3.2.2	Modelling of the Gibbs Energy of the System	50
3.2.3	Critical Assessment of Thermodynamic Properties	51
3.3	Thermodynamic Databases – the Underlying Basis of the Modelling of Phase Diagrams and Thermodynamic Properties, Databases for Lead-Free Solders	51
3.3.1	Creation of the Thermodynamic Databases	52
3.3.2	Three Conditions of Consistency	52
3.3.3	Specialized Databases for the Modelling of Thermodynamic Properties of Systems Relevant for Lead-Free Solders	54
3.4	Application of the SOLDERS Database to Alloy Development	57
3.4.1	Modelling of Phase Diagrams and Thermodynamic Properties	58
3.4.2	Modelling of Other Properties	65
3.5	Conclusions	68
	References	68
4	Interaction of Sn-based Solders with Ni(P) Substrates: Phase Equilibria and Thermochemistry	71
	<i>Clemens Schmetterer, Rajesh Ganesan, and Herbert Ipser</i>	
4.1	Introduction	72
4.2	Binary Phase Equilibria	73
4.2.1	Literature Overview	73
4.2.2	New Experimental Results	77
4.3	Ternary Phase Equilibria Ni-P-Sn	85
4.3.1	Literature Overview	85
4.3.2	Experimental Results	86
4.4	Thermochemical Data	94
4.4.1	Literature Overview	95
4.4.2	New Experimental Results	99
4.5	Relevance of the Results and Conclusion	111
	Acknowledgments	113
	References	113

Thematic Area III: Microalloying to Improve Reliability	119
5 'Effects of Minor Alloying Additions on the Properties and Reliability of Pb-Free Solders and Joints'	121
<i>Sung K. Kang</i>	
5.1 Introduction	122
5.2 Controlling Ag ₃ Sn Plate Formation	125
5.3 Controlling the Undercooling of Sn Solidification	132
5.4 Controlling Interfacial Reactions	136
5.4.1 Dissolution of UBM and Surface Finishes	137
5.4.2 Cu-Sn Intermetallic Formation	138
5.4.3 Interfacial Void Formation	143
5.4.4 Spalling of Ni-Sn Intermetallics	144
5.5 Modifying the Microstructure of SAC	145
5.6 Improving Mechanical Properties	149
5.6.1 Strength and Hardness	149
5.6.2 Drop Impact Resistance	150
5.6.3 Thermal Fatigue Resistance	150
5.7 Enhancing Electromigration Resistance	151
5.8 Summary	153
References	154
6 Development and Characterization of Nano-composite Solder	161
<i>Johan Liu, Si Chen, and Lilei Ye</i>	
6.1 Introduction	162
6.2 Nano-composite Solder Fabrication Process	162
6.2.1 Nano-particle Fabrication	162
6.2.2 Nano-composite Solder Fabrication	163
6.3 Microstructure	166
6.3.1 Grain Size	166
6.3.2 IMC Layer	167
6.4 Physical Properties	167
6.4.1 Viscosity	167
6.4.2 Melting Point	168
6.4.3 Wettability	168
6.4.4 CTE	168
6.4.5 Density and Young's Modulus	169
6.5 Mechanical Properties	169
6.5.1 Microhardness	169
6.5.2 Creep Resistance	170
6.5.3 Mechanical Strength	170
6.5.4 Ductility	170
6.6 Challenges and Solutions	171
6.7 Summary	174

Acknowledgments	175
References	176
Thematic Area IV: Chemical Issues Affecting Reliability	179
7 Chemical Changes for Lead-Free Soldering and Their Effect on Reliability	181
<i>Laura J. Turbini</i>	
7.1 Introduction	181
7.2 Soldering Fluxes and Pastes	181
7.3 Cleaning	185
7.4 Laminates	185
7.5 Halogen-Free Laminates	186
7.5.1 Z-axis CTE	187
7.5.2 Interconnect Stress Test (IST)	187
7.5.3 Time to Delamination	187
7.5.4 Temperature to Decomposition	188
7.6 Conductive Anodic Filament (CAF) Formation	189
7.7 Summary	193
References	193
Thematic Area V: Mechanical Issues Affecting Reliability	195
8 Influence of Microstructure on Creep and High Strain Rate Fracture of Sn-Ag-Based Solder Joints	197
<i>P. Kumar, Z. Huang, I. Dutta, G. Subbarayan, and R. Mahajan</i>	
8.1 Introduction	198
8.2 Coarsening Kinetics: Quantitative Analysis of Microstructural Evolution	199
8.2.1 Experimental Procedure	199
8.2.2 Results and Discussion	200
8.3 Creep Behavior of Sn-Ag-Based Solders and the Effect of Aging	206
8.3.1 Experimental Procedure	206
8.3.2 Results and Discussion	207
8.4 Role of Microstructure on High Strain Rate Fracture	219
8.4.1 Experimental and Analytical Procedure	220
8.4.2 Results and Discussion	222
8.5 Summary and Conclusions	227
Acknowledgments	227
References	228
9 Microstructure and Thermomechanical Behavior Pb-Free Solders	233
<i>D.R. Frear</i>	
9.1 Introduction	233
9.2 Sn-Pb Solder	234

9.3	Pb-Free Solders	237
9.3.1	Pb-Free Solders Microstructure	238
9.3.2	Interfacial Intermetallic Formation of Pb-Free Solders	240
9.3.3	Mechanical Metallurgy of Pb-Free Solder Alloys	243
9.3.4	Thermomechanical Fatigue Behavior of Pb-Free Solder Alloys	245
9.4	Summary	248
	References	249
10	Electromechanical Coupling in Sn-Rich Solder Interconnects	251
	<i>Q.S. Zhu, H.Y. Liu, L. Zhang, Q.L. Zeng, Z.G. Wang, and J.K. Shang</i>	
10.1	Introduction	252
10.2	Experimental	253
10.3	Results	255
10.3.1	Surface Morphology of Sn-3.5Ag-0.7Cu Interconnects after Electromigration	255
10.3.2	Surface Morphology of Pure Sn Interconnect after Electromigration	256
10.3.3	Surface Morphology of Single-Crystal Sn Interconnect after Electromigration	257
10.3.4	Tensile Strength of Solder Interconnects after Electromigration	258
10.3.5	Stress-Relaxation Behavior of Solder Interconnects after Electromigration	260
10.4	Discussion	264
10.4.1	Stress Induced by Vacancy Concentration at the Grain Boundary	264
10.4.2	Compression Stress Induced by the Cu_6Sn_5 Formation on the Surface	265
10.4.3	Vacancy-Concentration Distribution after Current Stressing	266
10.4.4	Effect of High Vacancy Concentration on Strength	267
10.4.5	Effect of High Vacancy Concentration on Stress-Relaxation Rate	268
10.5	Conclusions	269
	Acknowledgments	270
	References	270
11	Effect of Temperature-Dependent Deformation Characteristics on Thermomechanical Fatigue Reliability of Eutectic Sn-Ag Solder Joints	273
	<i>Andre Lee, Deep Choudhuri, and K.N. Subramanian</i>	
11.1	Introduction	274
11.2	Experimental Details	275
11.2.1	Test-Specimen Preparation	275
11.2.2	Thermal Cycling	275
11.2.3	Microstructural Characterization	276
11.2.4	Mechanical Testing	276

11.3	Results and Discussion	276
11.3.1	Effects of Temperature	277
11.3.2	Effects of Strain Rate	283
11.3.3	Influence of Temperature Regime of TMF on the Residual Mechanical Properties	286
11.3.4	Effect of Temperature Regime of TMF on Surface-Damage Accumulation	289
11.3.5	Evolution of Microstructural Damages during Low-Temperature Regime TMF	291
11.4	Summary and Conclusions	294
	References	295
Thematic Area VI: Whisker Growth Issues Affecting Reliability		297
12	Sn Whiskers: Causes, Mechanisms and Mitigation Strategies	299
	<i>Nitin Jadhav and Eric Chason</i>	
12.1	Introduction	299
12.2	Features of Whisker Formation	303
12.3	Understanding the Relationship between IMC Growth, Stress and Whisker Formation	308
12.4	Summary Picture of Whisker Formation	314
12.5	Strategies to Mitigate Whisker Formation	316
12.6	Conclusion	318
	Acknowledgments	318
	References	318
13	Tin Whiskers	323
	<i>Katsuaki Suganuma</i>	
13.1	Low Melting Point Metals and Whisker Formation	323
13.2	Room-Temperature Tin Whiskers on Copper Substrate	325
13.3	Thermal-Cycling Whiskers on 42 Alloy/Ceramics	326
13.4	Oxidation/Corrosion Whiskers	329
13.5	Mechanical-Compression Whiskers in Connectors	330
13.6	Electromigration Whiskers	331
13.7	Whisker Mitigation	332
13.8	Future Work	334
	References	334
Thematic Area VII: Electromigration Issues Affecting Reliability		337
14	Electromigration Reliability of Pb-Free Solder Joints	339
	<i>Seung-Hyun Chae, Yiwei Wang, and Paul S. Ho</i>	
14.1	Introduction	339
14.2	Failure Mechanisms of Solder Joints by Forced Atomic Migration	342

14.2.1	EM	342
14.2.2	TM	347
14.3	IMC Growth	351
14.3.1	Under Thermal Aging	351
14.3.2	Under Current Stressing	358
14.4	Effect of Sn Grain Structure on EM Reliability	363
14.5	Summary	366
	Acknowledgments	369
	References	369
15	Electromigration in Pb-Free Solder Joints in Electronic Packaging	375
	<i>Chih Chen, Shih-Wei Liang, Yuan-Wei Chang, Hsiang-Yao Hsiao, Jung Kyu Han, and K.N. Tu</i>	
15.1	Introduction	376
15.2	Unique Features for EM in Flip-Chip Pb-Free Solder Joints	376
15.2.1	Serious Current-Crowding Effect	377
15.2.2	Joule Heating and Nonuniform Temperature Distribution During EM	378
15.2.3	Effect of Current Crowding and Joule Heating on EM Failure	382
15.2.4	Thermomigration in Solder Joints	385
15.3	Changes of Physical Properties of Solder Bumps During EM	386
15.3.1	Electrical Resistance	386
15.3.2	Temperature Redistribution	390
15.3.3	Mechanical Properties: Electromigration-Induced Brittleness in Solder Joints	391
15.4	Challenges for Understanding EM in Pb-Free Solder Microbumps	393
15.4.1	Fast Dissolution of Cu and Ni under EM	393
15.4.2	Effect of Grain Orientation on Electromigration	393
15.4.3	Stress in Solder Bumps	393
15.5	Thermomigration of Cu and Ni in Pb-Free Solder Microbumps	394
15.6	Summary	394
	Acknowledgments	395
	References	395
16	Effects of Electromigration on Electronic Solder Joints	401
	<i>Sinn-wen Chen, Chih-ming Chen, Chao-hong Wang, and Chia-ming Hsu</i>	
16.1	Introduction	401
16.2	Effects of Electromigration on Solders	402
16.2.1	Solder Joints with Primarily Only One Moving Species	403
16.2.2	Solder Joints with Significant Hillock and Void Formation	404
16.2.3	Solder Joints with Phase Segregation	405

16.3	Effects of Electromigration on Interfacial Reactions	408
16.3.1	Asymmetric IMC Layer Growth (Electron from Solder to Substrate: Enhancement, Electron from Substrate to Solder: Suppression)	408
16.3.2	Asymmetric IMC Layer Growth (Electron from Solder to Substrate: Suppression, Electron from Substrate to Solder: Enhancement): Peltier Effect	409
16.3.3	Symmetric IMC Layer Growth (Cathode and Anode: Enhancement or Suppression)	411
16.3.4	No Effect with Passage of Electric Current	411
16.3.5	Effects of Electromigration on Reaction Phases: Evolution of Reaction Phase and Alternating Layer Formation	411
16.3.6	Microstructural Changes Caused by Electromigration	412
16.4	Modeling Description of Effects of Electromigration on IMC Growth	414
16.4.1	The Atomic Flux Summation Model	414
16.4.2	The Atomic Flux Summation with Stress Modification Model	415
16.4.3	Generalized Modeling for Growth of IMC Layer	416
16.5	Conclusions	418
	Acknowledgments	418
	References	418
Thematic Area VIII: Thermomigration Issues Affecting Reliability		423
17	Thermomigration in SnPb and Pb-Free Flip-Chip Solder Joints	425
	<i>Tian Tian, K.N. Tu, Hsiao-Yun Chen, Hsiang-Yao Hsiao, and Chih Chen</i>	
17.1	Introduction	425
17.2	Thermomigration in SnPb Flip-Chip Solder Joints	427
17.2.1	Thermomigration in Unpowered Composite SnPb Solder Joints	427
17.2.2	<i>In-Situ</i> Observation of Thermomigration in Composite SnPb Solder Joints	429
17.2.3	Thermomigration in Unpowered Eutectic SnPb Solder Joints	431
17.3	Thermomigration in Pb-Free Flip-Chip Solder Joints	432
17.3.1	Thermomigration of Cu and Ni in Pb-Free Flip-Chip Solder Joints	435
17.4	Driving Force of Thermomigration	435
17.4.1	Irreversible Processes of Thermomigration	438
17.5	Coupling between Thermomigration and Creep	439
17.6	Coupling between Thermomigration and Electromigration: Thermoelectric Effect on Electromigration	441
17.7	Summary	441
	Acknowledgments	442
	References	442

Thematic Area IX: Miniaturization Issues Affecting Reliability	443
18 Influence of Miniaturization on Mechanical Reliability of Lead-Free Solder Interconnects	445
<i>Golta Khatibi, Herbert Ipser, Martin Lederer, and Brigitte Weiss</i>	
18.1 Introduction	445
18.2 Effect of Miniaturization on Static Properties of Solder Joints (Tensile and Shear)	448
18.2.1 Constraint and Geometry Effects in Model Joints	448
18.2.2 Constraining Effects in Actual Joints	466
18.2.3 Fracture Mechanics Considerations of Solder Joints	473
18.3 Creep and Relaxation of Solder Joints	475
18.4 Summary and Conclusions	478
References	482
Index	487